

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc1605-lig#trpbf

(Engineering Calculation)

SSOP

(printed on: 2020-07-11 21:41:05)

**TOTAL MASS (g) : 0.239626**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.009889	1000000	41268.4882812		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.122431	975000	510925.46875		
		Iron (Fe)	7439-89-6	0.003014	24000	12577.9365234		
		Phosphorus (P)	7723-14-0	0.000038	300	158.580490112		
		Zinc (Zn)	7440-66-6	0.000088	700	367.239044189		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.125571</b>	<b>1000000</b>	<b>524029.1875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.003749	1000000	15644.9326172		
		<b>External Plating Total:</b>				<b>0.003749</b>	<b>1000000</b>	<b>15644.9326172</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001005	1000000	4194.03662109		
<b>Internal Plating Total:</b>				<b>0.001005</b>	<b>1000000</b>	<b>4194.03662109</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.002146	750000	8955.625		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000715	250000	2983.81689453		
<b>Die Attach Total:</b>				<b>0.002861</b>	<b>1000000</b>	<b>11939.4404297</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.009848	103000	41097.3828125		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.085571	895000	357102.40625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000191	2000	797.075622559		
		<b>Encapsulation Total:</b>				<b>0.095610</b>	<b>1000000</b>	<b>398996.875</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000941	1000000	3926.95385742		
					<b>TOTAL MASS (g) :</b>	<b>0.239626</b>		